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News Fact Sheet

Note to Editors: Multimedia is available at: www.intel.com/pressroom/idf

Intel Developer Forum Day 2: News Disclosures

April 14, 2010 – Intel Corporation is holding its Intel Developer Forum in Beijing from April 13-14. Below are brief summaries and news highlights from Doug Davis' and Justin Rattner's keynotes.

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Doug Davis, "Connected, Intelligent, Pervasive: Transformations in Embedded Computing"
Vice President and General Manager, Embedded and Communications Group, Intel
Doug Davis disclosed information about a future Intel System on Chip (SoC) product, highlighted significant advancements with customers in China and discussed the Intel Embedded Design Center. Details about the news from Davis' keynote are described below.

- **Tunnel Creek** –
  - *System design flexibility in a small form factor* – Tunnel Creek is an SoC that can be connected with any PCIexpress*-compliant device, resulting in lower development costs and enabling developers to implement Intel® Atom^{TM} processors in smaller form factor designs than ever before, such as IP media phones and in-vehicle-infotainment systems.
  - *Atom for deeply embedded applications* – The I/O flexibility for Tunnel Creek makes the processor ideal for applications that require standard interconnects, such as USB for IP Cameras; applications with diverse I/O requirements, such as programmable logic controllers for industrial automation applications; applications with existing proprietary I/O requirements, such as print imaging appliances; and applications that would benefit from customized I/O solutions, such as in-vehicle infotainment devices.
  - *Enhanced graphics and performance* – Tunnel Creek also features enhanced graphics capabilities for devices in the car and the home. For example, with in-vehicle infotainment systems, the front-seat display could have 3D mapping while the back-seat simultaneously displays improved gaming graphics.

- **In-Vehicle Infotainment** –
  - *Advanced before-market infotainment systems* – Mr. Wang Dian Ming, vice chairman of Rongcheng HawTai Automobile*, discussed how the company's B11* sedan will be the first car to include an Intel Atom processor-based in-vehicle-infotainment system with standard car production manufacturing. The system will include the MeeGo* operating system, which will enable users to download car maintenance

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updates such as service reminders and diagnostic checks, as well as entertainment applications such as music, real-time weather and navigation, on-demand from an online store.

o *Improved graphics and device integration* - Davis was joined on-stage by Doug Welk, Chief Engineer, Advanced Infotainment and Driver Interface, Delphi* Electronics and Safety. Welk demonstrated Delphi's next-generation Intel Atom processor-based in-car infotainment system on a device that featured a dual-display with enhanced 3D graphics. Bringing the familiarity and usability of a smart phone into a car, the Delphi system demonstrated that users could wirelessly port applications and a phone user interface directly from a smart phone into the in-vehicle device display.

o *Next-Generation Standards-based Hardware* – Davis demonstrated an in-vehicle infotainment compute module that includes the Intel Atom processor, I/O chipset and a standard connector. Developed in conjunction with Harman International Automotive Division*, the component modularity enables customers to scale implementation of the system from entry-level to high-end head units, with integration capabilities for current and next-generation Intel Atom processors, all while reducing costs and improving time-to-market.

- **Digital Signage –**
  o *Enhancing the in-store shopping experience* - Davis was joined on-stage by Rowan Lodge, Head of Retail Development, Region Asia Pacific, Adidas*, who addressed how the Intel processor-based digital signage technology in Adidas' Beijing retail store has changed the way customers interact with merchandise, making the shopping experience more informative and entertaining. Lodge also discussed how digital signage technology enables retailers such as Adidas to stay competitive for consumer attention; for example, the digital signage technology allows Adidas to present merchandise in a more compelling context, such as displaying footwear in conjunction with a demonstration of the in-shoe technology. In addition to having Intel processor-based technology in the Beijing store, Lodge also noted plans to implement Intel-processor based solutions in Adidas' Brand Centre in Shanghai.

- **Embedded Design Center –**
  o Davis also addressed the Embedded Design Center on the company Web site, an online resource that provides developers with information about the latest Intel products and assistance with technical questions including personalized help from Intel engineers. The Embedded Design Center also has an embedded board planning tool for printed circuit board design. The tool includes features such as board sizing, component placement, routing issues assistance, power budgeting and thermal analysis. For more information, visit http://edc.intel.com.

- **Telecommunications –**
  o *Innovation in a booming wireless market* – Dr. Cui, Chunfeng, manager of wireless research labs, department of wireless communications, China Mobile* Research Institute, joined Davis on-stage to confirm that the next generation of infrastructure systems for China Mobile would be developed on Intel architecture to help the

wireless telecommunications company not only cope with increasing network demands, but also address the company's need for mobile network consolidation.

o *Benefits of developing on a single architecture* - Addressing telecom operators' needs for high performance, integration, reliability, scalability, maintainability and low power consumption, worldwide leaders in telecommunications manufacturing Alcatel-Lucent*, Ericsson*, Huawei* and ZTE*confirmed support of Intel architecture for the companies' next generation of telecommunications systems infrastructure.

Justin Rattner, "Personal Energy Management"
Vice President and Chief Technology Officer, Intel Senior Fellow and Director, Intel Labs
Rattner discussed how smarter technology can reduce and better manage energy consumption. He said the company's goal is to extend Intel technology into more PC-like and single function devices that empower consumers and businesses to make better energy choices. Details about the news from Rattner's keynote are described below.

- **Intelligent Home Energy Management –**
  o Researchers at Intel are exploring opportunities to make the collection of energy data easy and low cost for consumers. Rattner said Intel has developed a low-cost sensor prototype that could be easily deployed by consumers to analyze energy usage loads of devices and appliances throughout a home.
  o Rattner showed a concept device for managing energy consumption powered by an Intel Atom processor. The demonstration showed how a homeowner could use the intelligent electronic dashboard to monitor how much energy connected appliances in the home are using. It also showed how the device could encourage new habits for reducing energy use by providing ongoing information and suggestions on energy use. For example, a homeowner could activate custom settings on the touch screen display to modify the thermostat temperature, turn off some appliances, or switch on the security screen.

- **Electric Cars -**
  o Rattner also discussed improving personal energy management with electric cars. He said as the volume of electric cars increase, strain will be placed on the electric grid at night when most are recharging. Intel Labs is looking at how to better coordinate charging to reduce peak loads, which could also save money.

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